

## 2.5-V PHASE-LOCKED-LOOP CLOCK DRIVER

### FEATURES

- Spread-Spectrum Clock Compatible
- Operating Frequency: 60 MHz to 220 MHz
- Low Jitter (Cycle-Cycle):  $\pm 35$  ps
- Low Static Phase Offset:  $\pm 50$  ps
- Low Jitter (Period):  $\pm 30$  ps
- 1-to-10 Differential Clock Distribution (SSTL2)
- Best in Class for  $V_{OX} = V_{DD}/2 \pm 0.1$  V
- Operates From Dual 2.6-V or 2.5-V Supplies
- Available in a 40-Pin MLF Package, 48-Pin TSSOP Package, 56-Ball MicroStar Junior™ BGA Package
- Consumes  $< 100$ - $\mu$ A Quiescent Current
- External Feedback Pins (FBIN,  $\overline{\text{FBIN}}$ ) Are Used to Synchronize the Outputs to the Input Clocks
- Meets/Exceeds JEDEC Standard (JESD82-1) For DDRI-200/266/333 Specification
- Meets/Exceeds Proposed DDRI-400 Specification (JESD82-1A)
- Enters Low-Power Mode When No CLK Input Signal Is Applied or PWRDWN Is Low

### APPLICATIONS

- DDR Memory Modules (DDR400/333/266/200)
- Zero-Delay Fan-Out Buffer

### DESCRIPTION

The CDCVF857 is a high-performance, low-skew, low-jitter, zero-delay buffer that distributes a differential clock input pair (CLK,  $\overline{\text{CLK}}$ ) to 10 differential pairs of clock outputs ( $\text{Y}[0:9]$ ,  $\overline{\text{Y}}[0:9]$ ) and one differential pair of feedback clock outputs (FBOUT,  $\overline{\text{FBOUT}}$ ). The clock outputs are controlled by the clock inputs (CLK,  $\overline{\text{CLK}}$ ), the feedback clocks (FBIN,  $\overline{\text{FBIN}}$ ), and the analog power input (AVDD). When PWRDWN is high, the outputs switch in phase and frequency with CLK. When  $\overline{\text{PWRDWN}}$  is low, all outputs are disabled to a high-impedance state (3-state) and the PLL is shut down (low-power mode). The device also enters this low-power mode when the input frequency falls below a suggested detection frequency that is below 20 MHz (typical 10 MHz). An input frequency detection circuit detects the low frequency condition and, after applying a  $>20$ -MHz input signal, this detection circuit turns the PLL on and enables the outputs.

When  $\text{AV}_{DD}$  is strapped low, the PLL is turned off and bypassed for test purposes. The CDCVF857 is also able to track spread spectrum clocking for reduced EMI.

Because the CDCVF857 is based on PLL circuitry, it requires a stabilization time to achieve phase-lock of the PLL. This stabilization time is required following power up. The CDCVF857 is characterized for both commercial and industrial temperature ranges.

### AVAILABLE OPTIONS

$T_A$	TSSOP (DGG)	40-Pin MLF	56-Ball BGA <sup>(1)</sup>
$-40^\circ\text{C}$ to $85^\circ\text{C}$	CDCVF857DGG	CDCVF857RTB	CDCVF857GQL
$-40^\circ\text{C}$ to $85^\circ\text{C}$		CDCVF857RHA	CDCVF857ZQL

(1) Maximum load recommended is 12 pF for 200 MHz. At 12-pF load, maximum  $T_A$  allowed is  $70^\circ\text{C}$ .

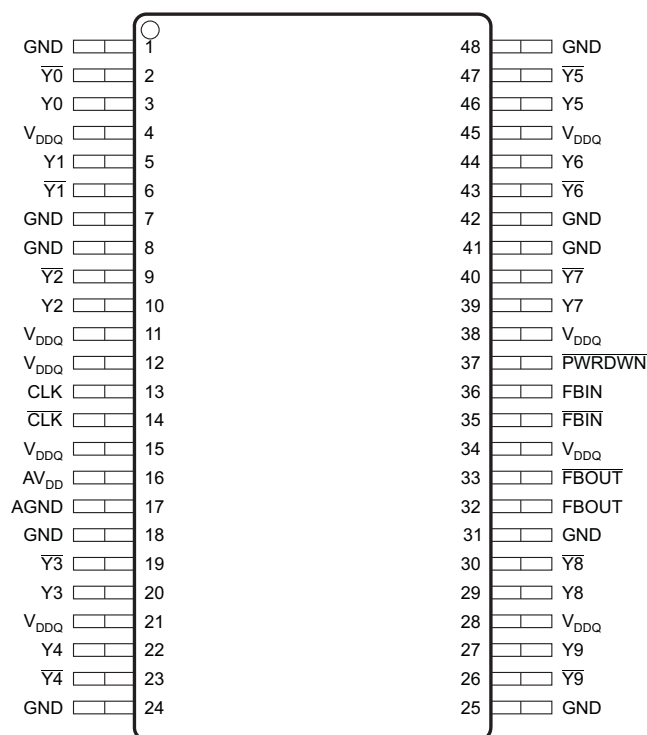


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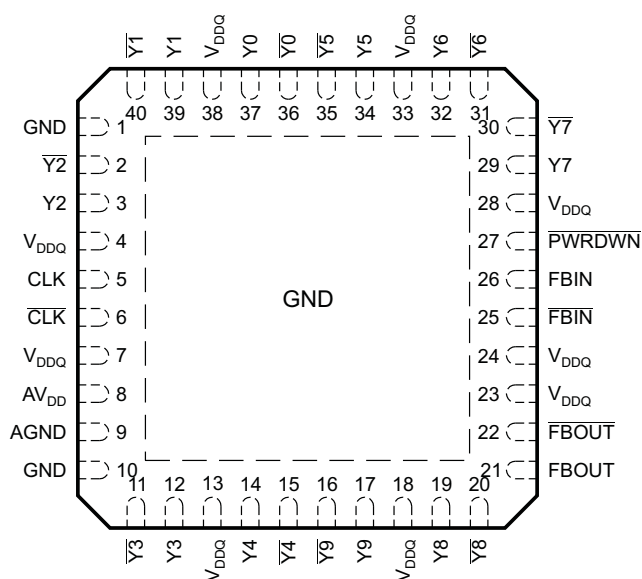
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## FUNCTION TABLE (Select Functions)

INPUTS				OUTPUTS				PLL
AVDD	PWRDWN	CLK	CLK	Y[0:9]	Y[0:9]	FBOUT	FBOUT	
GND	H	L	H	L	H	L	H	Bypassed/off
GND	H	H	L	H	L	H	L	Bypassed/off
X	L	L	H	Z	Z	Z	Z	Off
X	L	H	L	Z	Z	Z	Z	Off
2.5 V (nom)	H	L	H	L	H	L	H	On
2.5 V (nom)	H	H	L	H	L	H	L	On
2.5 V (nom)	X	<20 MHz	<20 MHz	Z	Z	Z	Z	Off

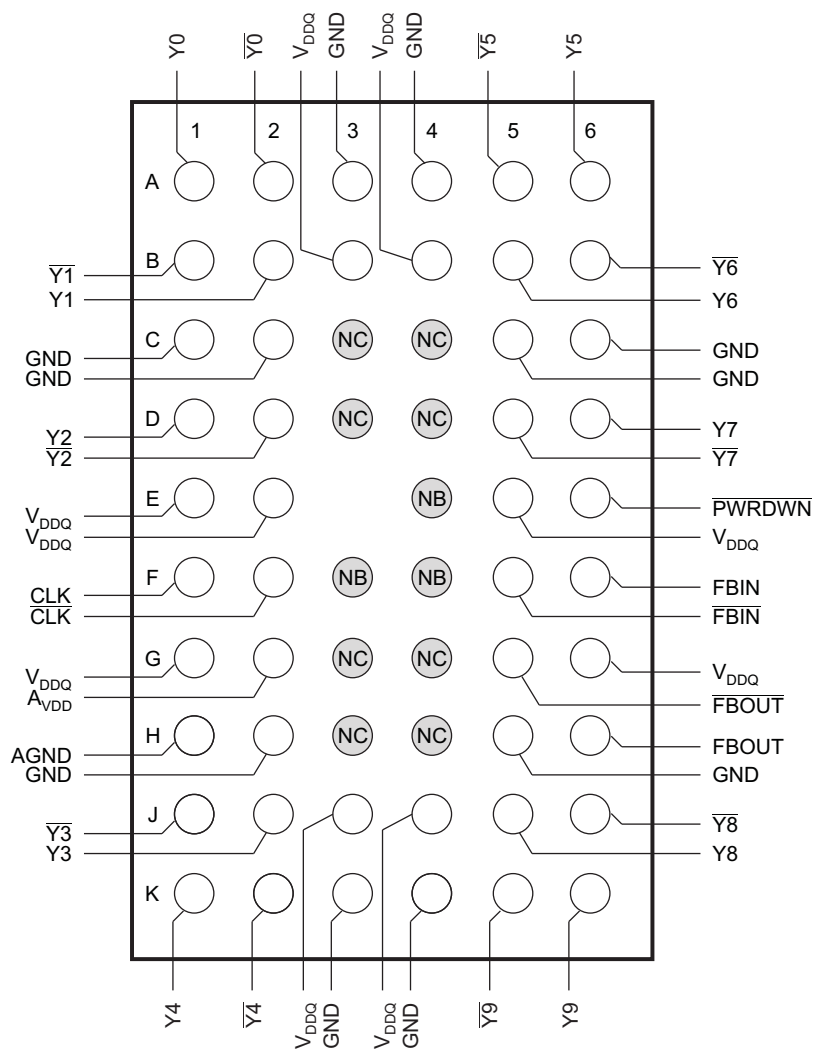
DGG PACKAGE  
(TOP VIEW)

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RHA/RTB PACKAGE  
(TOP VIEW)

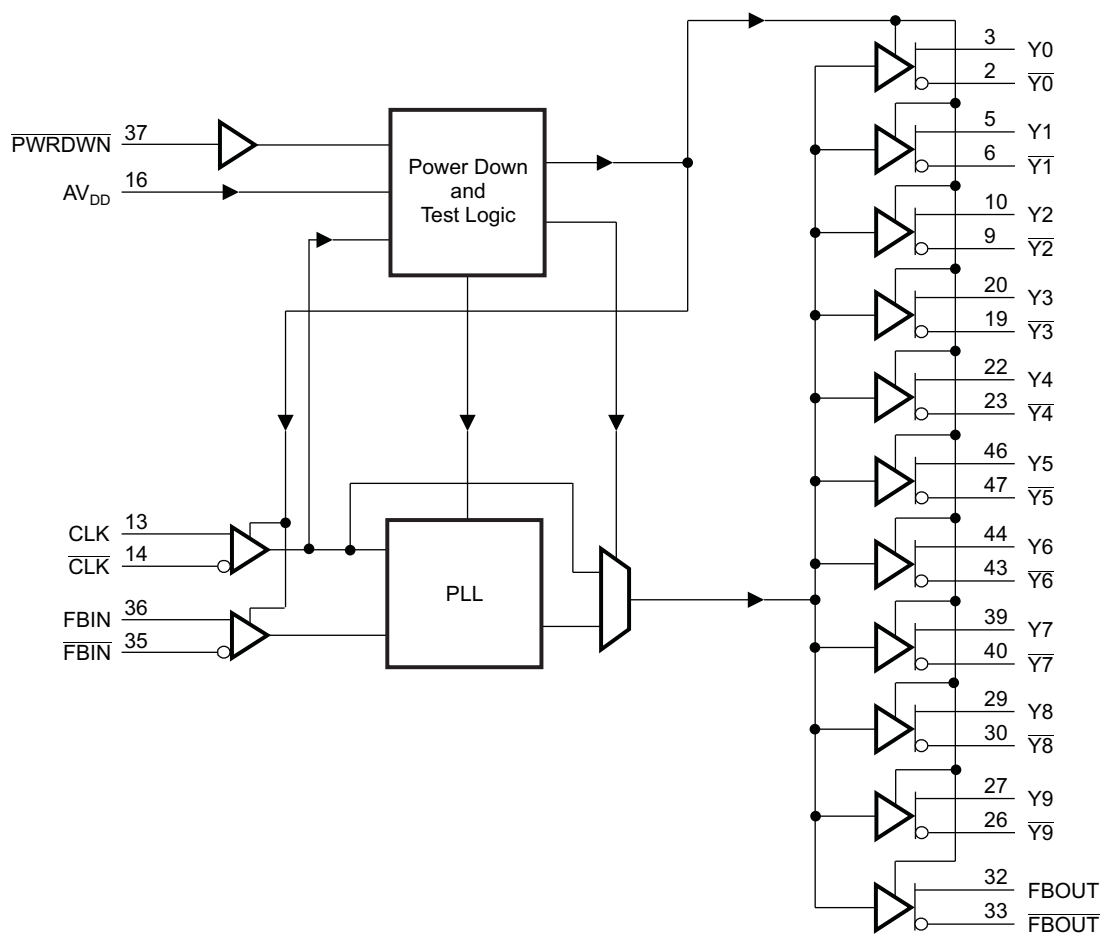
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MicroStar Junior™ BGA (GQL/ZQL) PACKAGE  
(TOP VIEW)



NB = No Ball  
NC = No Connection

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**FUNCTIONAL BLOCK DIAGRAM**

B0196-01

**Table 1. TERMINAL FUNCTIONS**

TERMINAL				I/O	DESCRIPTION
NAME	DGG	RHA/RTB	GQL/ZQL		
AGND	17	9	H1	–	Ground for 2.5-V analog supply
AV <sub>DD</sub>	16	8	G2	–	2.5-V analog supply
CLK, $\overline{\text{CLK}}$	13, 14	5, 6	F1, F2	I	Differential clock input
FBIN, FBIN	35, 36	25, 26	F5, F6	I	Feedback differential clock input
FBOU <sub>T</sub> , FBOU <sub>T</sub>	32, 33	21, 22	H6, G5	O	Feedback differential clock output
GND	1, 7, 8, 18, 24, 25, 31, 41, 42, 48	1, 10	A3, A4, C1, C2, C5, C6, H2, H5, K3, K4	–	Ground
PWRDWN	37	27	E6	I	Output enable for Y and $\overline{\text{Y}}$
V <sub>DDQ</sub>	4, 11, 12, 15, 21, 28, 34, 38, 45	4, 7, 13, 18, 23, 24, 28, 33, 38	B3, B4, E1, E2, E5, G1, G6, J3, J4	–	2.5-V supply
Y0, $\overline{\text{Y0}}$	3, 2	37, 36	A1, A2	O	Buffered output copies of input clock, CLK, $\overline{\text{CLK}}$
Y1, $\overline{\text{Y1}}$	5, 6	39, 40	B2, B1	O	
Y2, $\overline{\text{Y2}}$	10, 9	3, 2	D1, D2	O	
Y3, $\overline{\text{Y3}}$	20, 19	12, 11	J2, J1	O	
Y4, $\overline{\text{Y4}}$	22, 23	14, 15	K1, K2	O	
Y5, $\overline{\text{Y5}}$	46, 47	34, 35	A6, A5	O	
Y6, $\overline{\text{Y6}}$	44, 43	32, 31	B5, B6	O	
Y7, $\overline{\text{Y7}}$	39, 40	29, 30	D6, D5	O	
Y8, $\overline{\text{Y8}}$	29, 30	19, 20	J5, J6	O	
Y9, $\overline{\text{Y9}}$	27, 26	17, 16	K6, K5	O	

## ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) <sup>(1)</sup>

V <sub>DDQ</sub> , AV <sub>DD</sub>	Supply voltage range		0.5 V to 3.6 V
V <sub>I</sub>	Input voltage range <sup>(2)(3)</sup>		–0.5 V to V <sub>DDQ</sub> + 0.5 V
V <sub>O</sub>	Output voltage range <sup>(2)(3)</sup>		–0.5 V to V <sub>DDQ</sub> + 0.5 V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0 or V <sub>I</sub> > V <sub>DDQ</sub>	±50 mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0 or V <sub>O</sub> > V <sub>DDQ</sub>	±50 mA
I <sub>O</sub>	Continuous output current	V <sub>O</sub> = 0 to V <sub>DDQ</sub>	±50 mA
I <sub>DDC</sub>	Continuous current to GND or V <sub>DDQ</sub>		±100 mA
T <sub>stg</sub>	Storage temperature range		–65°C to 150°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
- (3) This value is limited to 3.6 V maximum.

## THERMAL CHARACTERISTICS

R <sub>θJA</sub> for TSSOP (DGG) Package <sup>(1)</sup>			R <sub>θJA</sub> for MLF (RHA/RTB) Package		R <sub>θJA</sub> for BGA (GQL/ZQL) Package <sup>(2)</sup>	
Airflow	Low K	High K	Airflow	With 4 Thermal Vias	Airflow	High K
0 ft/min	89.1°C/W	70°C/W	0 ft/min	44.7°C/W	0 ft/min	132.2°C/W
150 ft/min	78.5°C/W	65.3°C/W	150 ft/min		150 ft/min	126.4°C/W

- (1) The package thermal impedance is calculated in accordance with JESD 51.
- (2) Connecting the NC-balls (C3, C4, D3, D4, G3, G4, H3, H4) to a ground plane improves the θ<sub>JA</sub> to 114.8°C/W (0 airflow).

**RECOMMENDED OPERATING CONDITIONS**

			MIN	NOM	MAX	UNIT
Supply voltage	V <sub>DDQ</sub>	PC1600 – PC3200	2.3		2.7	V
	AVDD		V <sub>DDQ</sub> – 0.12		2.7	
V <sub>IL</sub> Low-level input voltage	CLK, $\overline{\text{CLK}}$ , FBIN, $\overline{\text{FBIN}}$				V <sub>DDQ</sub> /2 – 0.18	V
	PWRDWN		–0.3		0.7	
V <sub>IH</sub> High-level input voltage	CLK, $\overline{\text{CLK}}$ , FBIN, $\overline{\text{FBIN}}$		V <sub>DDQ</sub> /2 + 0.18			V
	PWRDWN		1.7		V <sub>DDQ</sub> + 0.3	
DC input signal voltage <sup>(1)</sup>			–0.3		V <sub>DDQ</sub> + 0.3	V
V <sub>ID</sub> Differential input signal voltage <sup>(2)</sup>	DC	CLK, FBIN	0.36		V <sub>DDQ</sub> + 0.6	V
	AC	CLK, FBIN	0.7		V <sub>DDQ</sub> + 0.6	
V <sub>IX</sub> Input differential pair cross voltage <sup>(3)(4)</sup>			V <sub>DDQ</sub> /2 – 0.2		V <sub>DDQ</sub> /2 + 0.2	V
I <sub>OH</sub> High-level output current					–12	mA
I <sub>OL</sub> Low-level output current					12	mA
SR Input slew rate			1		4	V/ns
T <sub>A</sub> Operating free-air temperature			–40		85	°C

(1) The unused inputs must be held high or low to prevent them from floating.

(2) The dc input signal voltage specifies the allowable dc execution of the differential input.

(3) The differential input signal voltage specifies the differential voltage |V<sub>TR</sub> – V<sub>CP</sub>| required for switching, where V<sub>TR</sub> is the true input level and V<sub>CP</sub> is the complementary input level.

(4) The differential cross-point voltage tracks variations of V<sub>CC</sub> and is the voltage at which the differential signals must cross.

**ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>IK</sub> Input voltage, all inputs	V <sub>DDQ</sub> = 2.3 V, I <sub>I</sub> = –18 mA			–1.2	V
V <sub>OH</sub> High-level output voltage	V <sub>DDQ</sub> = min to max, I <sub>OH</sub> = –1 mA	V <sub>DDQ</sub> – 0.1			V
	V <sub>DDQ</sub> = 2.3 V, I <sub>OH</sub> = –12 mA	1.7			
V <sub>OL</sub> Low-level output voltage	V <sub>DDQ</sub> = min to max, I <sub>OL</sub> = 1 mA			0.1	V
	V <sub>DDQ</sub> = 2.3 V, I <sub>OL</sub> = 12 mA			0.6	
V <sub>OD</sub> Output voltage swing <sup>(2)</sup>	Differential outputs are terminated with 120 Ω, C <sub>L</sub> = 14 pF (see Figure 3)	1.1		V <sub>DDQ</sub> – 0.4	V
V <sub>OX</sub> Output differential cross-voltage <sup>(3)</sup>		V <sub>DDQ</sub> /2 – 0.1	V <sub>DDQ</sub> /2	V <sub>DDQ</sub> /2 + 0.1	V
I <sub>I</sub> Input current	V <sub>DDQ</sub> = 2.7 V, V <sub>I</sub> = 0 V to 2.7 V			±10	μA
I <sub>OZ</sub> High-impedance-state output current	V <sub>DDQ</sub> = 2.7 V, V <sub>O</sub> = V <sub>DDQ</sub> or GND			±10	μA
I <sub>DDPD</sub> Power-down current on V <sub>DDQ</sub> + AV <sub>DD</sub>	CLK and $\overline{\text{CLK}}$ = 0 MHz; PWRDWN = Low; Σ of I <sub>DD</sub> and A <sub>I</sub> <sub>DD</sub>		20	100	μA
A <sub>I</sub> <sub>DD</sub> Supply current on AV <sub>DD</sub>	f <sub>O</sub> = 170 MHz		6	8	mA
	f <sub>O</sub> = 200 MHz		8	10	
C <sub>I</sub> Input capacitance	V <sub>DDQ</sub> = 2.5 V, V <sub>I</sub> = V <sub>DDQ</sub> or GND	2	2.5	3.5	pF
I <sub>DD</sub> Dynamic current on V <sub>DDQ</sub>	Without load	f <sub>O</sub> = 170 MHz	120	140	mA
		f <sub>O</sub> = 200 MHz	125	150	
	Differential outputs terminated with 120 Ω, C <sub>L</sub> = 0 pF	f <sub>O</sub> = 170 MHz	220	270	
		f <sub>O</sub> = 200 MHz	230	280	
	Differential outputs terminated with 120 Ω, C <sub>L</sub> = 14 pF	f <sub>O</sub> = 170 MHz	280	330	
		f <sub>O</sub> = 200 MHz	300	350	

(1) All typical values are at nominal V<sub>DDQ</sub>.

(2) The differential output signal voltage specifies the differential voltage |V<sub>TR</sub> – V<sub>CP</sub>|, where V<sub>TR</sub> is the true output level and V<sub>CP</sub> is the complementary output level.

(3) The differential cross-point voltage tracks variations of V<sub>DDQ</sub> and is the voltage at which the differential signals must cross.

## ELECTRICAL CHARACTERISTICS (continued)

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP <sup>(1)</sup>	MAX	UNIT
$\Delta C$ Part-to-part input capacitance variation	$V_{DDQ} = 2.5\text{ V}$ , $V_I = V_{DDQ}$ or GND			1	pF
$C_{I(\Delta)}$ Input capacitance difference between CLK and $\overline{\text{CLK}}$ , FBIN, and $\overline{\text{FBIN}}$	$V_{DDQ} = 2.5\text{ V}$ , $V_I = V_{DDQ}$ or GND			0.25	pF

## TIMING REQUIREMENTS

over recommended ranges of supply voltage and operating free-air temperature

PARAMETER		MIN	MAX	UNIT
f <sub>CLK</sub>	Operating clock frequency	60	220	MHz
	Application clock frequency	90	220	
Input clock duty cycle		40%	60%	
Stabilization time (PLL mode) <sup>(1)</sup>			10	μs
Stabilization time (bypass mode) <sup>(2)</sup>			30	ns

- (1) The time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLK and  $V_{DD}$  must be applied. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable. This parameter does not apply for input modulation under SSC application.
- (2) A recovery time is required when the device goes from power-down mode into bypass mode ( $AV_{DD}$  at GND).

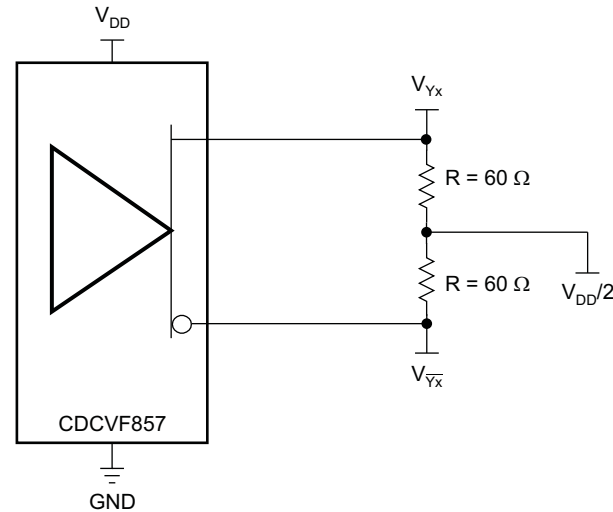
## SWITCHING CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{\text{PLH}}^{(1)}$ Low-to-high level propagation delay time	Test mode/CLK to any output		3.5		ns
$t_{\text{PHL}}^{(1)}$ High-to-low level propagation delay time	Test mode/CLK to any output		3.5		ns
$t_{\text{jit(per)}}^{(2)}$ Jitter (period), see <a href="#">Figure 7</a>	100 MHz (PC1600)	–65		65	ps
	133/167/200 MHz (PC2100/2700/3200)	–30		30	
$t_{\text{jit(cc)}}^{(2)}$ Jitter (cycle-to-cycle), see <a href="#">Figure 4</a>	100 MHz (PC1600)	–50		50	ps
	133/167/200 MHz (PC2100/2700/3200)	–35		35	
$t_{\text{jit(hper)}}^{(2)}$ Half-period jitter, see <a href="#">Figure 8</a>	100 MHz (PC1600)	–100		100	ps
	133/167/200 MHz (PC2100/2700/3200)	–75		75	
$t_{\text{slr(o)}}$ Output clock slew rate, see <a href="#">Figure 9</a>	Load: 120 $\Omega$ , 14 pF		1	2	V/ns
$t_{(\phi)}$ Static phase offset, see <a href="#">Figure 5</a>	100/133/167/200 MHz	–50		50	ps
$t_{\text{sk(o)}}$ Output skew, see <a href="#">Figure 6</a>	Load: 120 $\Omega$ , 14 pF; 100/133/167/200 MHz			40	ps

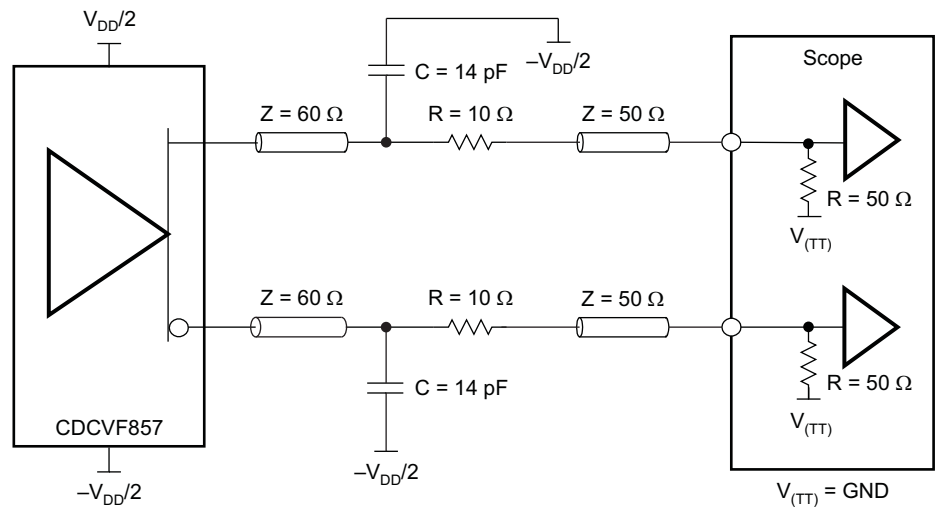
- (1) Refers to the transition of the noninverting output.
- (2) This parameter is assured by design but cannot be 100% production tested.

PARAMETER MEASUREMENT INFORMATION



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Figure 1. IBIS Model Output Load

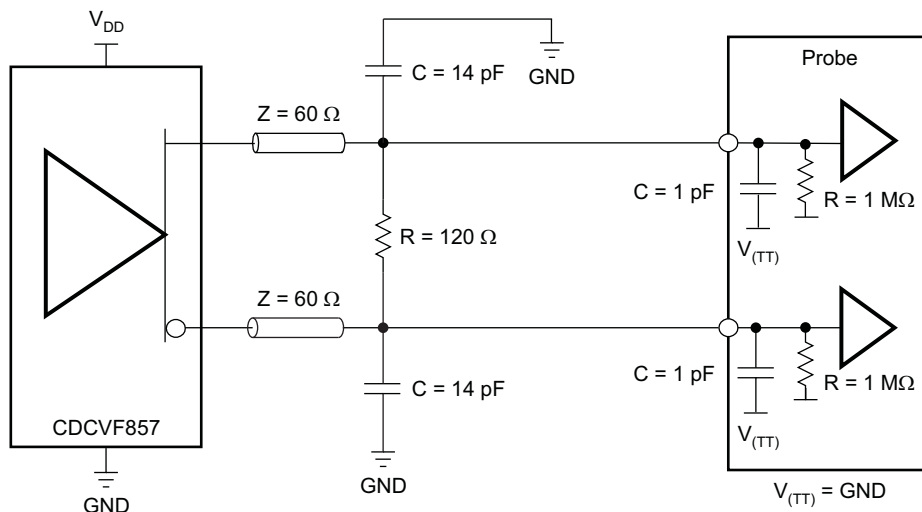


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Figure 2. Output Load Test Circuit

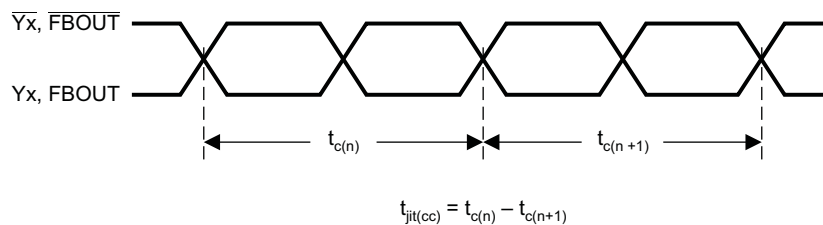


### PARAMETER MEASUREMENT INFORMATION (continued)



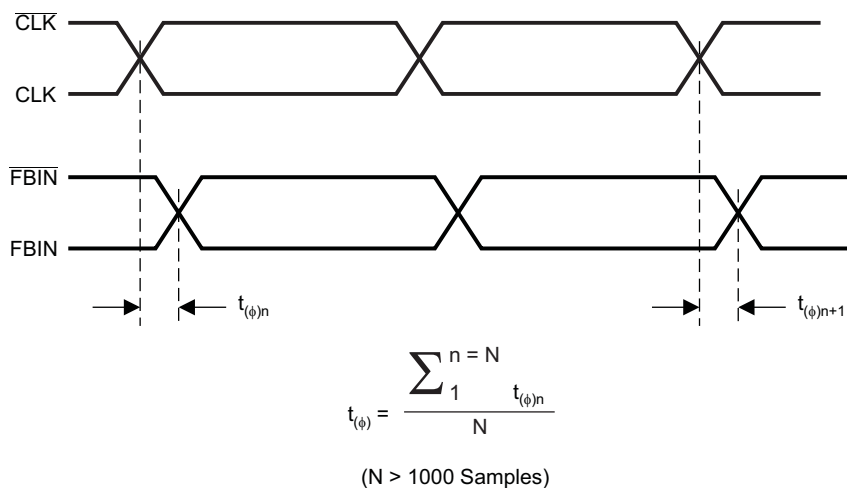
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**Figure 3. Output Load Test Circuit for Crossing Point**



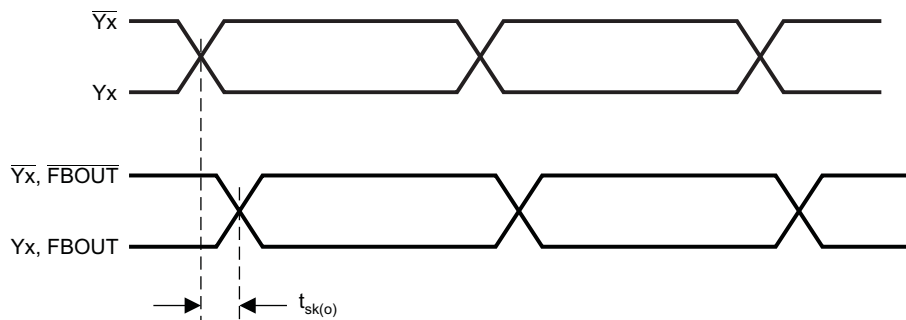
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### Figure 4. Cycle-to-Cycle Jitter

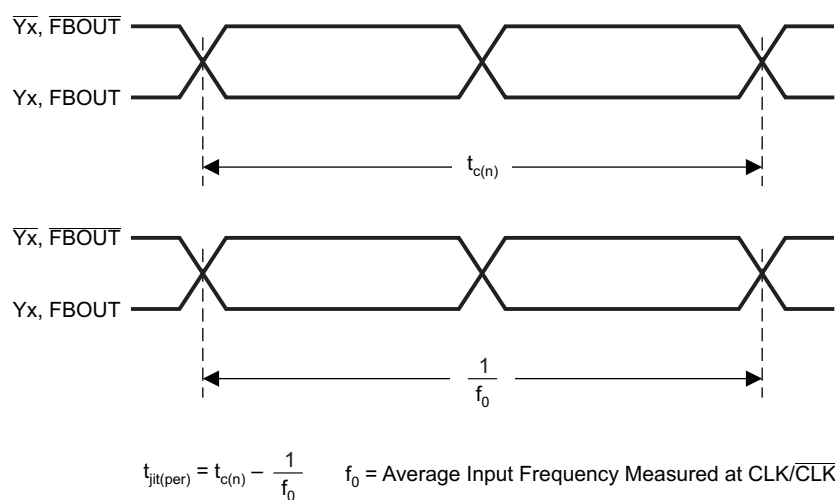


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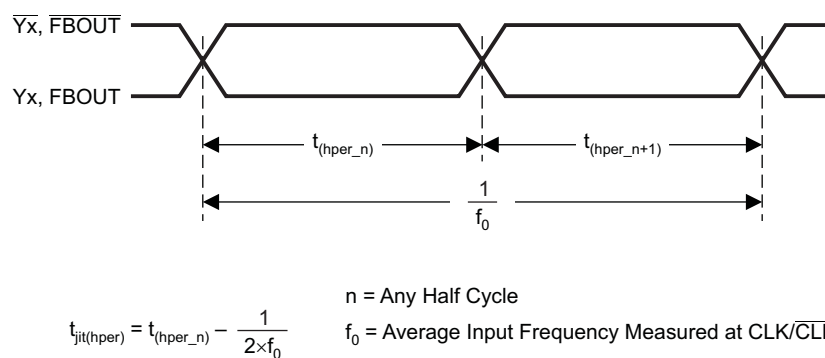
### Figure 5. Phase Offset

**PARAMETER MEASUREMENT INFORMATION (continued)**

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**Figure 6. Output Skew**

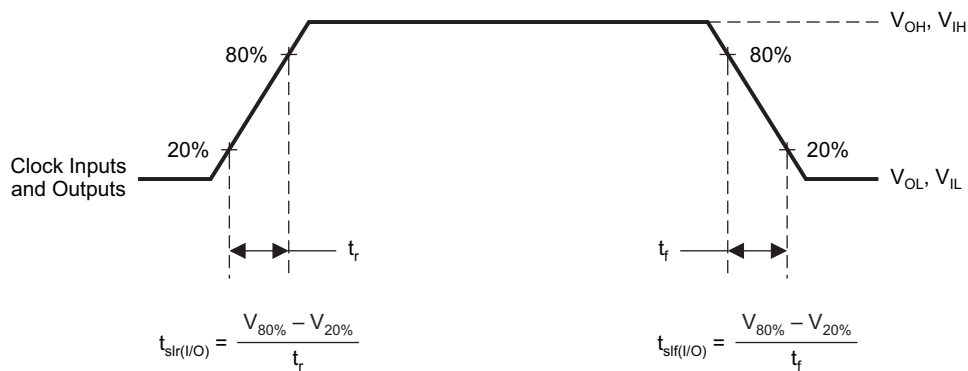
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**Figure 7. Period Jitter**

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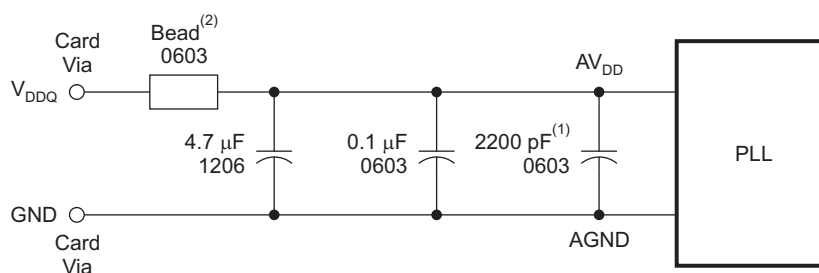
**Figure 8. Half-Period Jitter**

## PARAMETER MEASUREMENT INFORMATION (continued)



T0179-01

Figure 9. Input and Output Slew Rates



S0232-01

(1) Place the 2200-pF capacitor close to the PLL.

(2) Recommended bead: Fair-Rite P/N 2506036017Y0 or equivalent (0.8  $\Omega$  dc maximum, 600  $\Omega$  at 100 MHz).

NOTE: Use a wide trace for the PLL analog power and ground. Connect PLL and capacitors to AGND trace and connect trace to one GND via (farthest from the PLL).

Figure 10. Recommended AV<sub>DD</sub> Filtering

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
CDCVF857DGG	ACTIVE	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CDCVF857DGGG4	ACTIVE	TSSOP	DGG	48	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CDCVF857DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CDCVF857DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CDCVF857GQLR	ACTIVE	BGA MICROSTAR JUNIOR	GQL	56	1000	TBD	SNPB	Level-2A-220C-4 WKS
CDCVF857RHAR	ACTIVE	QFN	RHA	40	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
CDCVF857RHARG4	ACTIVE	QFN	RHA	40	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
CDCVF857RHAT	ACTIVE	QFN	RHA	40	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
CDCVF857RHATG4	ACTIVE	QFN	RHA	40	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
CDCVF857RTBR	ACTIVE	QFN	RTB	40	2500	TBD	CU SNPB	Level-3-235C-168 HR
CDCVF857RTBT	ACTIVE	QFN	RTB	40	250	TBD	CU SNPB	Level-3-235C-168 HR
CDCVF857ZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCVF857DGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
CDCVF857GQLR	BGA MICROSTAR JUNIOR	GQL	56	1000	330.0	16.4	4.8	7.3	1.45	8.0	16.0	Q1
CDCVF857RHAR	QFN	RHA	40	2500	330.0	16.4	6.3	6.3	1.5	12.0	16.0	Q2
CDCVF857RHAT	QFN	RHA	40	250	180.0	16.4	6.3	6.3	1.5	12.0	16.0	Q2
CDCVF857RTBR	QFN	RTB	40	2500	330.0	16.4	6.3	6.3	1.5	12.0	16.0	Q2
CDCVF857RTBT	QFN	RTB	40	250	330.0	16.4	6.3	6.3	1.5	12.0	16.0	Q2
CDCVF857ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.45	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS

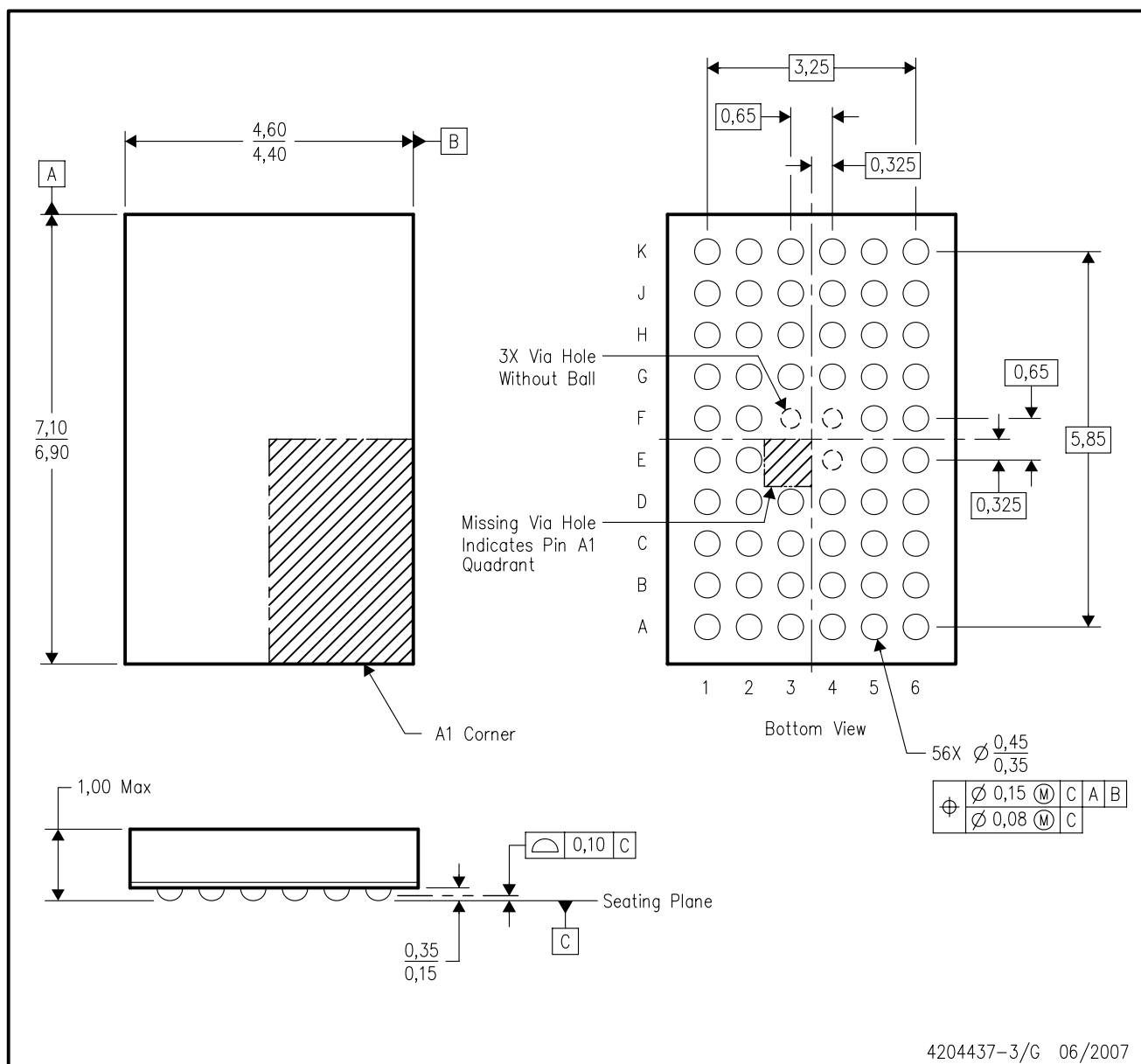


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCVF857DGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
CDCVF857GQLR	BGA MICROSTAR JUNIOR	GQL	56	1000	346.0	346.0	33.0
CDCVF857RHAR	QFN	RHA	40	2500	346.0	346.0	33.0
CDCVF857RHAT	QFN	RHA	40	250	190.5	212.7	31.8
CDCVF857RTBR	QFN	RTB	40	2500	333.2	345.9	28.6
CDCVF857RTBT	QFN	RTB	40	250	333.2	345.9	28.6
CDCVF857ZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	346.0	346.0	33.0

## ZQL (R-PBGA-N56)

## PLASTIC BALL GRID ARRAY



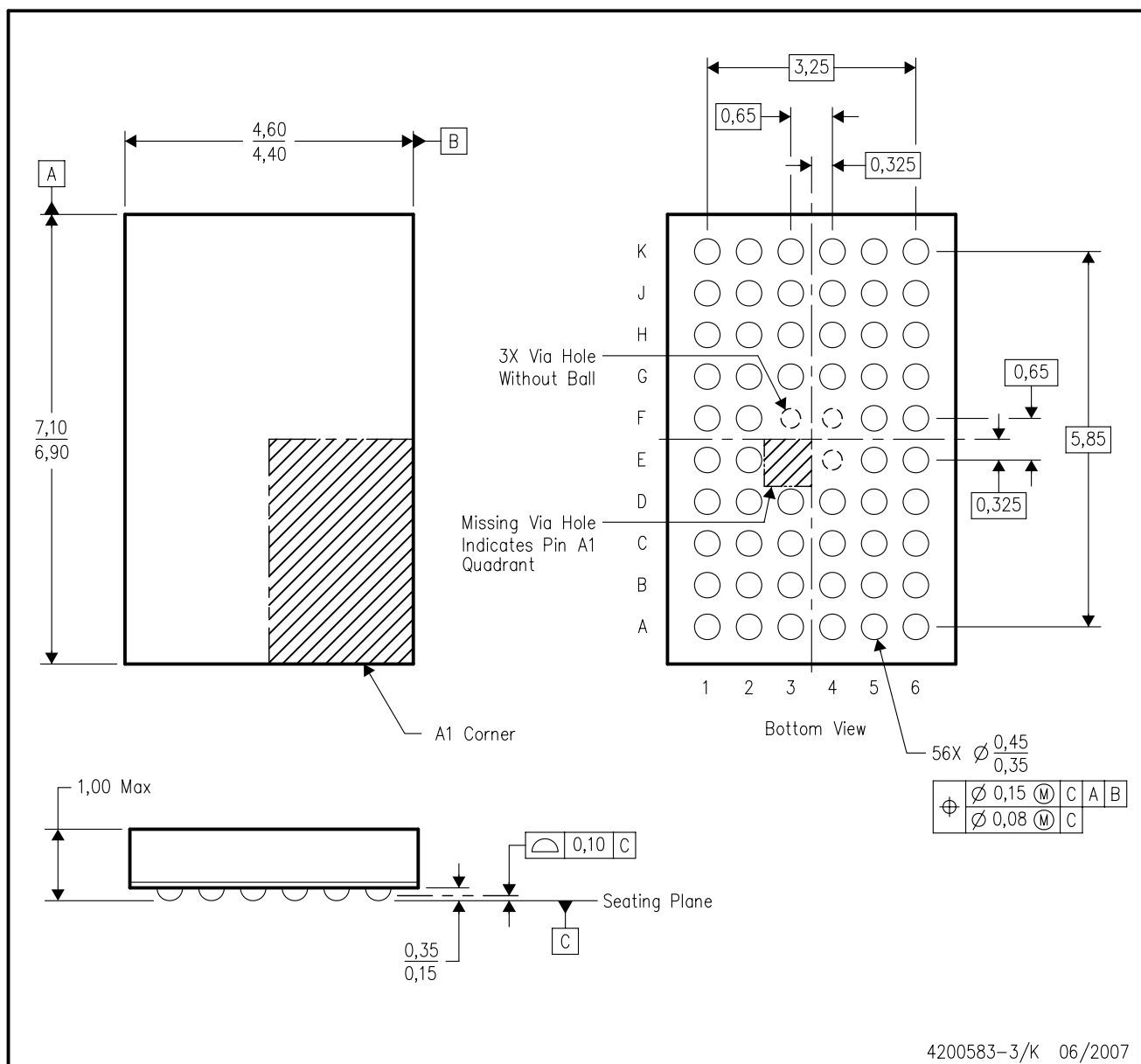
4204437-3/G 06/2007

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - Falls within JEDEC MO-285 variation BA-2.
  - This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).



## GQL (R-PBGA-N56)

## PLASTIC BALL GRID ARRAY



4200583-3/K 06/2007

- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - Falls within JEDEC MO-285 variation BA-2.
  - This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.

## DGG (R-PDSO-G\*\*)

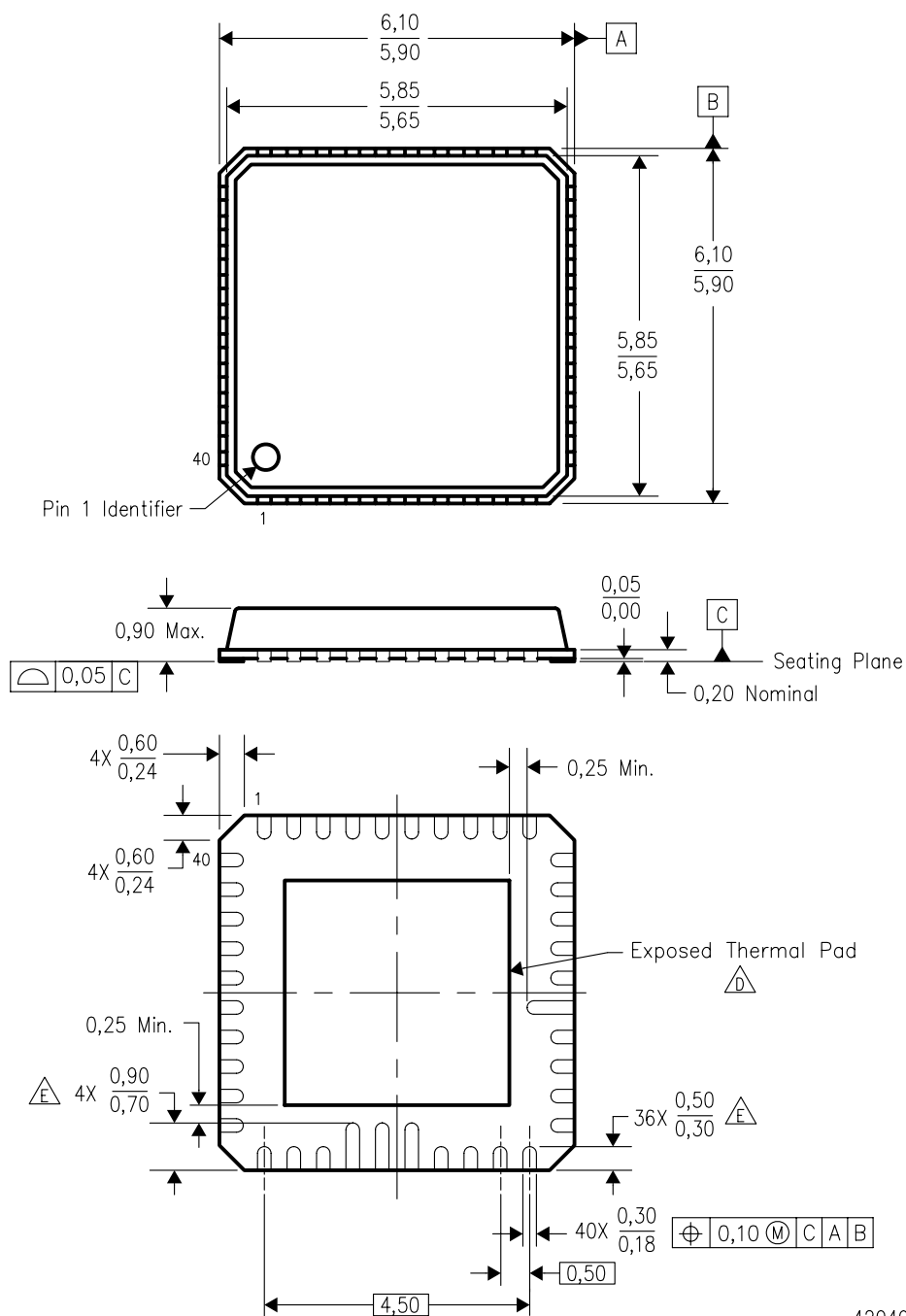
## PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

## RTB (S-PQFP-N40) \*LONG LEAD OPTION\* PLASTIC QUAD FLATPACK



4204967-3/E 05/07

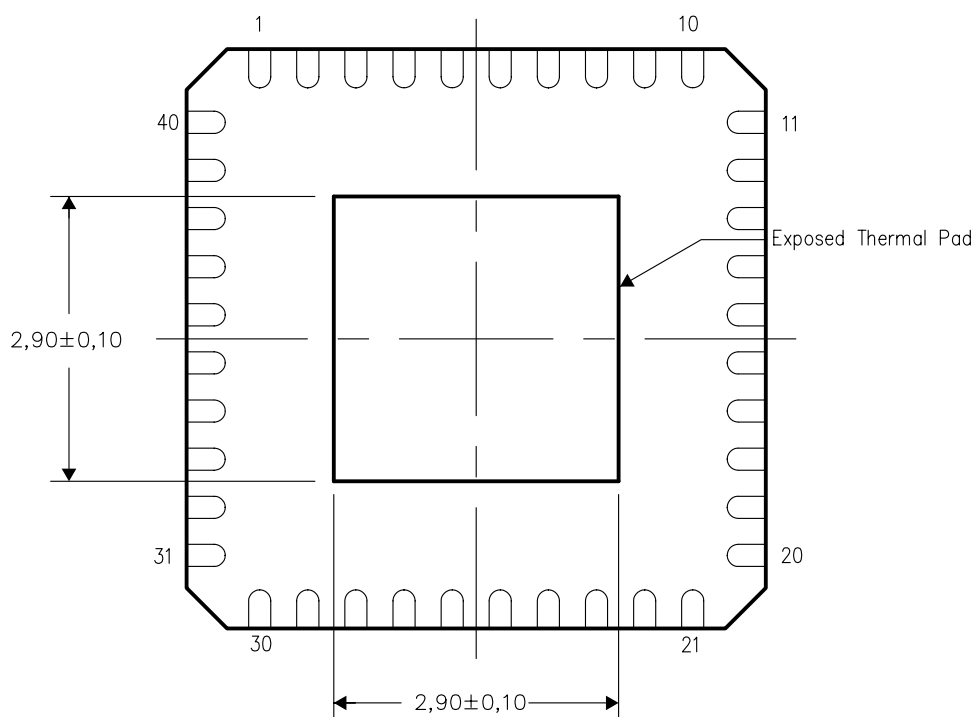
- NOTES: A. All linear dimensions are in millimeters.  
 Dimensioning and tolerancing per ASME Y14.5M-1994. The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.  
 B. This drawing is subject to change without notice.  
 C. QFN (Quad Flatpack No-Lead) Package configuration. Selected lands extended past 0,50 length.

## THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, Quad Flatpack No-Lead Logic Packages, Texas Instruments Literature No. SCBA017. This document is available at [www.ti.com](http://www.ti.com).

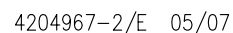
The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions



**△** The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.

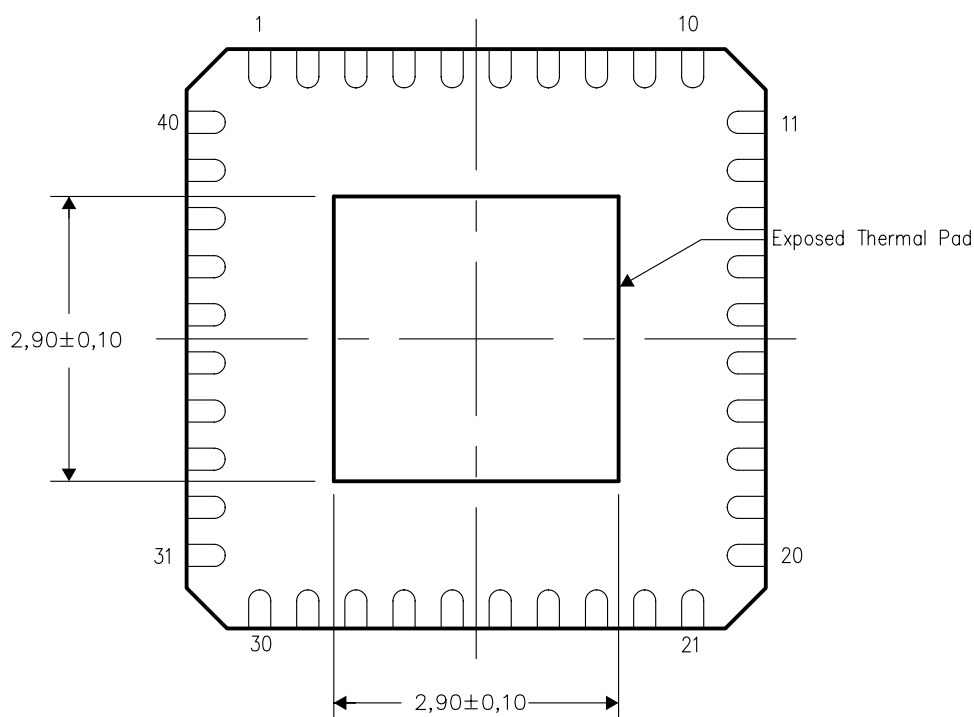
**△** Some products have selected lands extended past 0,50 length. See Product Data Sheet for details regarding specific land length exceptions.

## THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, Quad Flatpack No-Lead Logic Packages, Texas Instruments Literature No. SCBA017. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.



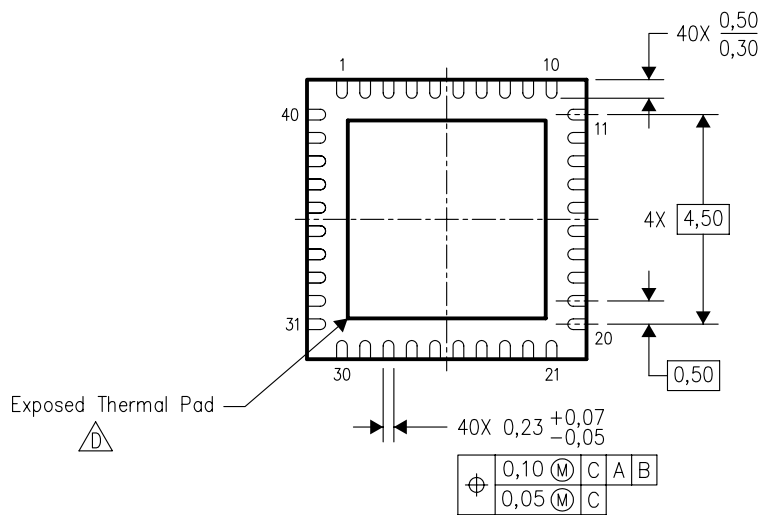
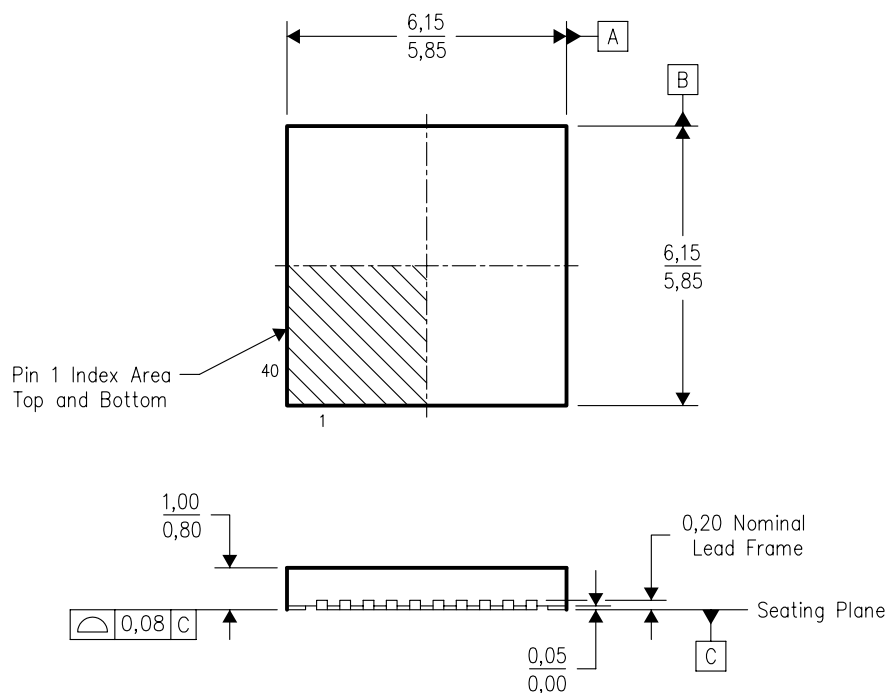
Bottom View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

RHA (S-PQFP-N40)

PLASTIC QUAD FLATPACK



Bottom View

4204276/C 12/2004

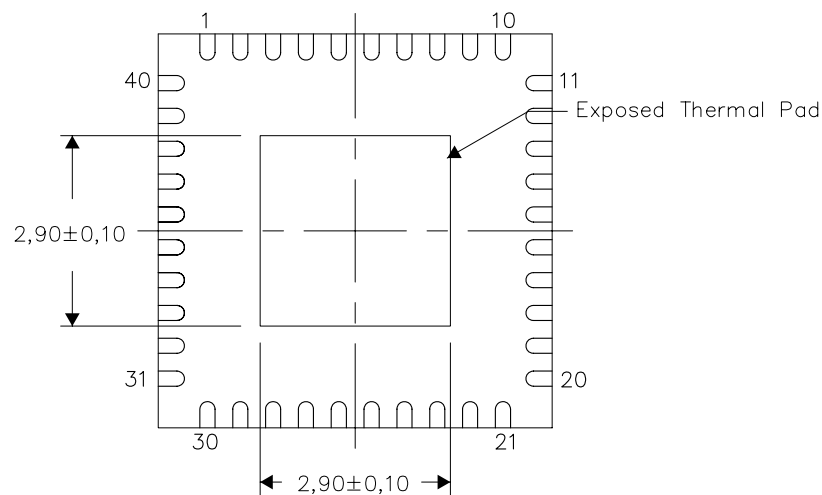
- NOTES:
- All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - QFN (Quad Flatpack No-Lead) Package configuration.
  - The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
  - Package complies to JEDEC MO-220 variation VJJD-2.

## THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at [www.ti.com](http://www.ti.com).

The exposed thermal pad dimensions for this package are shown in the following illustration.

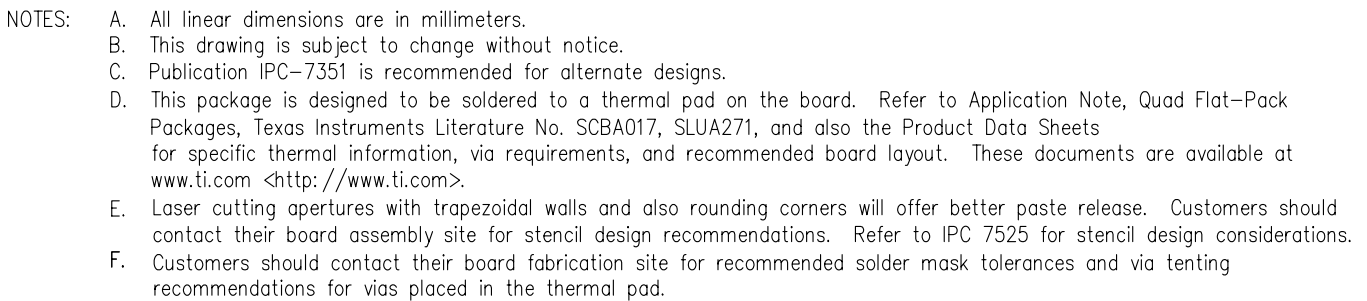


Bottom View

NOTE: All linear dimensions are in millimeters

## Exposed Thermal Pad Dimensions





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